

N-channel 600 V, 0.260 Ω typ., 12 A MDmesh™ DM2 Power MOSFET in a TO-220 package

Datasheet - production data

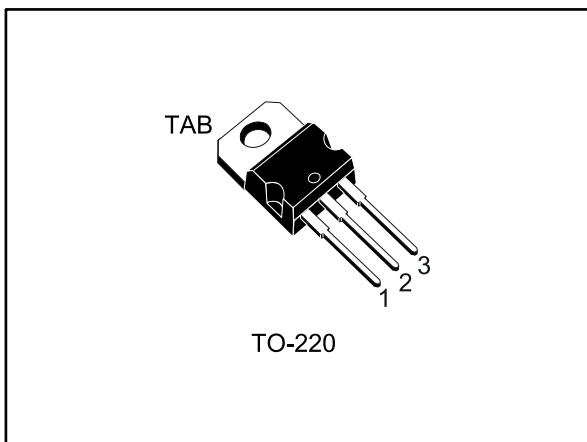
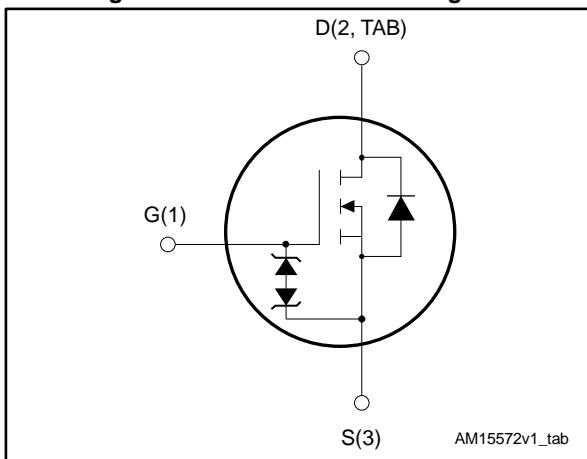


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STP18N60DM2	600 V	0.295 Ω	12 A

- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

Applications

- Switching applications

Description

This high voltage N-channel Power MOSFET is part of the MDmesh™ DM2 fast recovery diode series. It offers very low recovery charge (Q_{rr}) and time (t_{rr}) combined with low $R_{DS(on)}$, rendering it suitable for the most demanding high efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

Table 1: Device summary

Order code	Marking	Package	Packing
STP18N60DM2	18N60DM2	TO-220	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_{case} = 25^\circ\text{C}$	12	A
	Drain current (continuous) at $T_{case} = 100^\circ\text{C}$	7.6	
$I_{DM}^{(1)}$	Drain current (pulsed)	48	A
P_{TOT}	Total dissipation at $T_{case} = 25^\circ\text{C}$	90	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	40	V/ns
	MOSFET dv/dt ruggedness	50	
T_{stg}	Storage temperature	-55 to 150	$^\circ\text{C}$
T_j	Maximum junction temperature	150	

Notes:

(1) Pulse width is limited by safe operating area.

(2) $I_{SD} \leq 12$ A, $di/dt \leq 400$ A/ μs , $V_{DS(\text{peak})} < V_{(\text{BR})DSS}$, $V_{DD} = 80\%$ $V_{(\text{BR})DSS}$.(3) $V_{DS} \leq 480$ V.**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.39	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	62.5	

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
$I_{AR}^{(1)}$	Avalanche current, repetitive or not repetitive	2.5	A
$E_{AR}^{(2)}$	Single pulse avalanche energy	380	mJ

Notes:(1) Pulse width is limited by $T_{j\max}$.(2) starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50$ V.

2 Electrical characteristics

($T_{case} = 25^\circ\text{C}$ unless otherwise specified)

Table 5: Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	600			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$			1.5	μA
		$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_{case} = 125^\circ\text{C}$			100	
I_{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	3	4	5	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		0.260	0.295	Ω

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	800	-	pF
C_{oss}	Output capacitance		-	40	-	
C_{rss}	Reverse transfer capacitance		-	1.33	-	
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	80	-	pF
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	5.6	-	Ω
Q_g	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}$ (see Figure 14: "Gate charge test circuit")	-	20	-	nC
Q_{gs}	Gate-source charge		-	5.2	-	
Q_{gd}	Gate-drain charge		-	8.5	-	

Notes:

⁽¹⁾ $C_{oss \text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 6 \text{ A}$ $R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13: "Switching times test circuit for resistive load" and Figure 18: "Switching time waveform")	-	13.5	-	ns
t_r	Rise time		-	8	-	
$t_{d(off)}$	Turn-off-delay time		-	9.5	-	
t_f	Fall time		-	32.5	-	

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		12	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		48	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 12 \text{ A}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 12 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}, V_{DD} = 60 \text{ V}$ (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	125		ns
Q_{rr}	Reverse recovery charge		-	680		nC
I_{RRM}	Reverse recovery current		-	11		A
t_{rr}	Reverse recovery time	$I_{SD} = 12 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}, V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	190		ns
Q_{rr}	Reverse recovery charge		-	1200		nC
I_{RRM}	Reverse recovery current		-	13		A

Notes:

(1) Pulse width is limited by safe operating area

(2) Pulse test: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

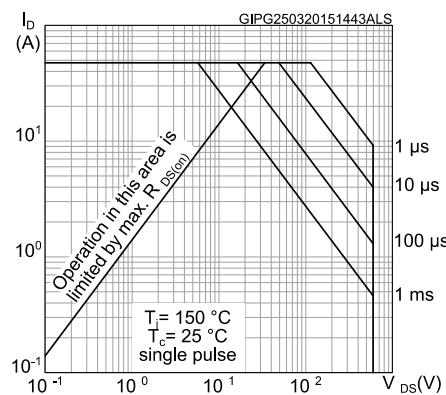
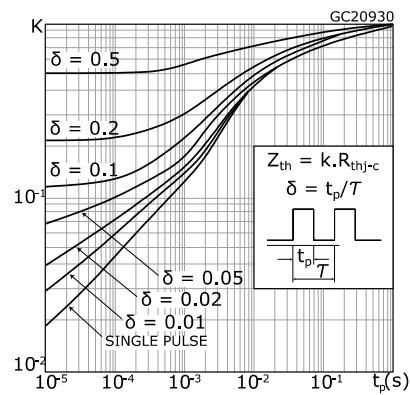
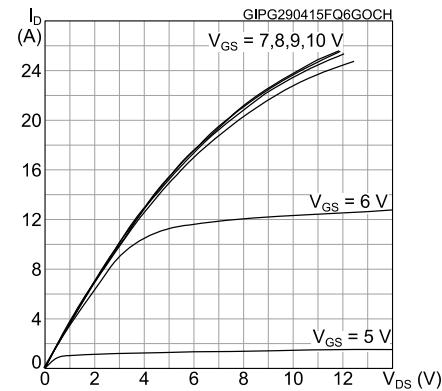
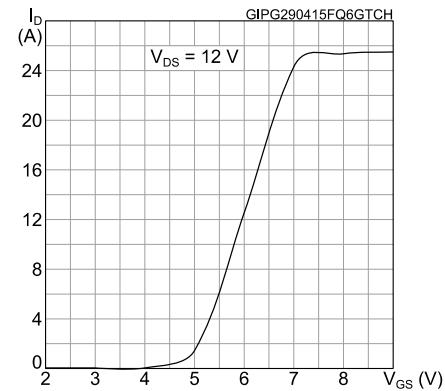
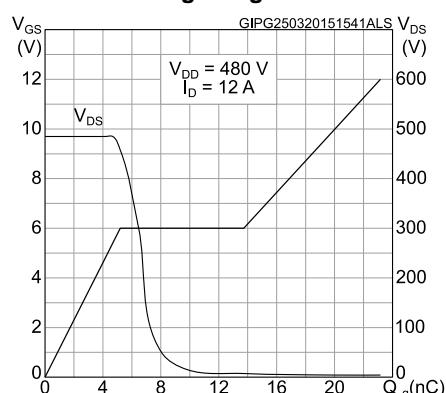
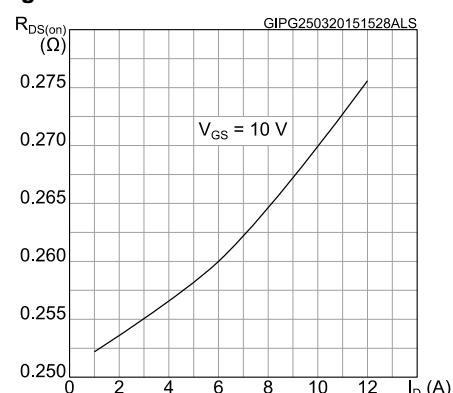
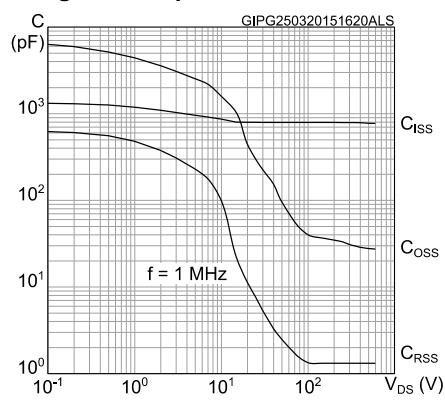
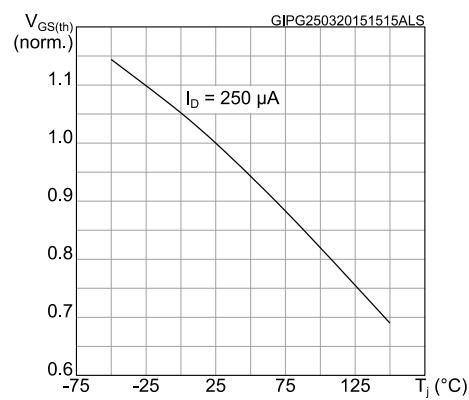
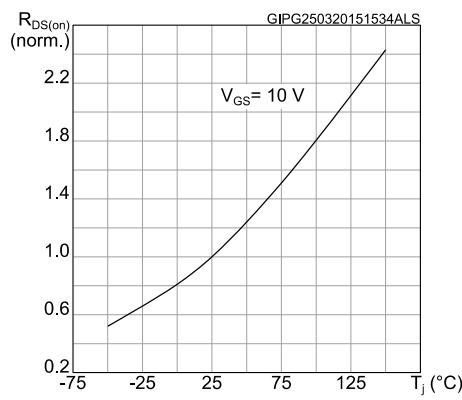
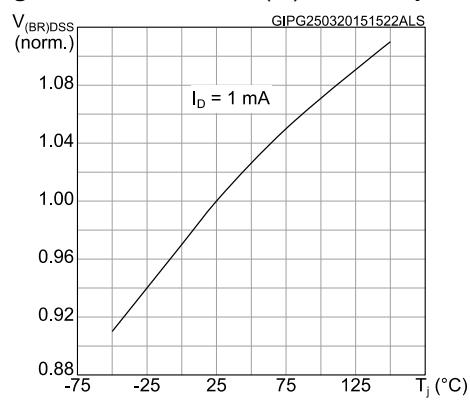
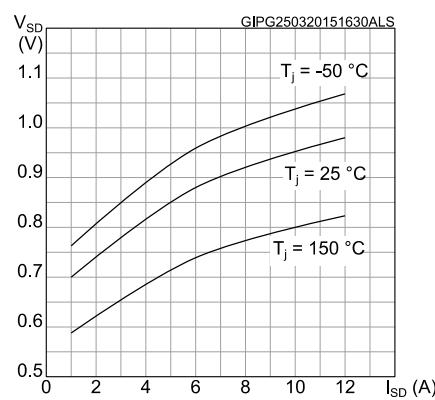
Figure 2: Safe operating area**Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Gate charge vs gate-source voltage****Figure 7: Static drain-source on-resistance**

Figure 8: Capacitance variations**Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized $V_{(BR)DSS}$ vs temperature****Figure 12: Source-drain diode forward characteristics**

3 Test circuits

Figure 13: Switching times test circuit for resistive load

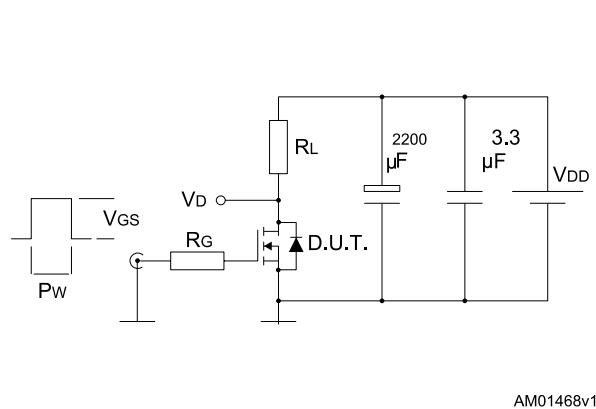


Figure 14: Gate charge test circuit

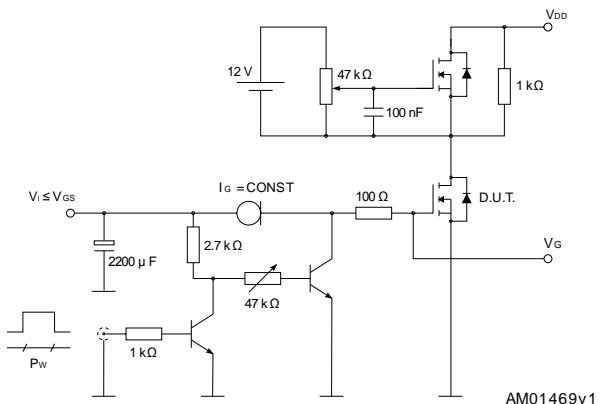


Figure 15: Test circuit for inductive load switching and diode recovery times

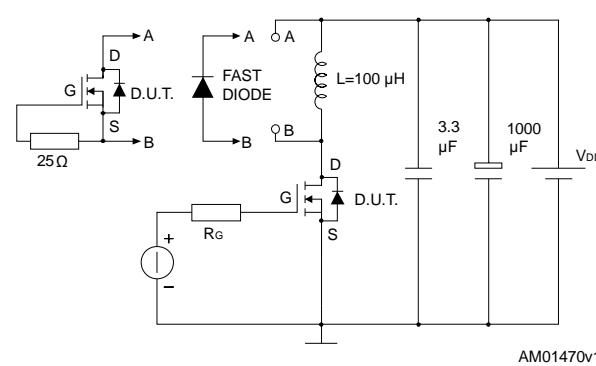


Figure 16: Unclamped inductive load test circuit

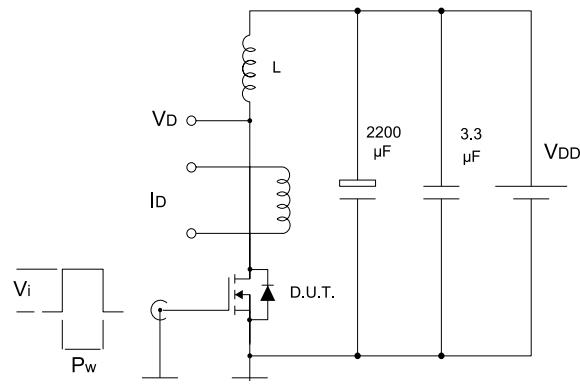


Figure 17: Unclamped inductive waveform

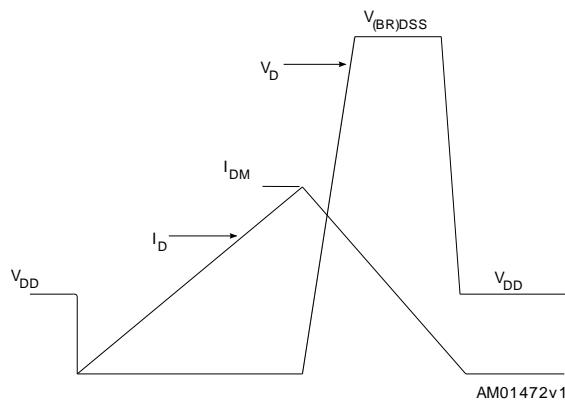
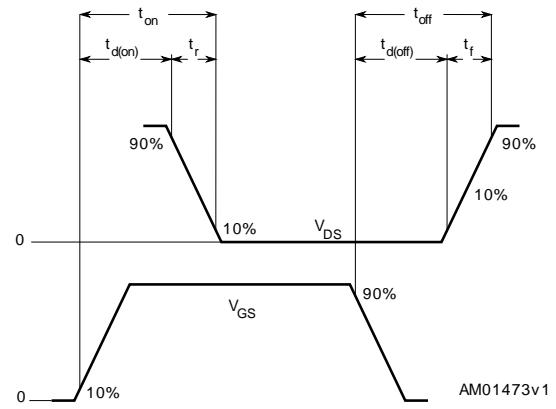


Figure 18: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 TO-220 type A package information

Figure 19: TO-220 type A package outline

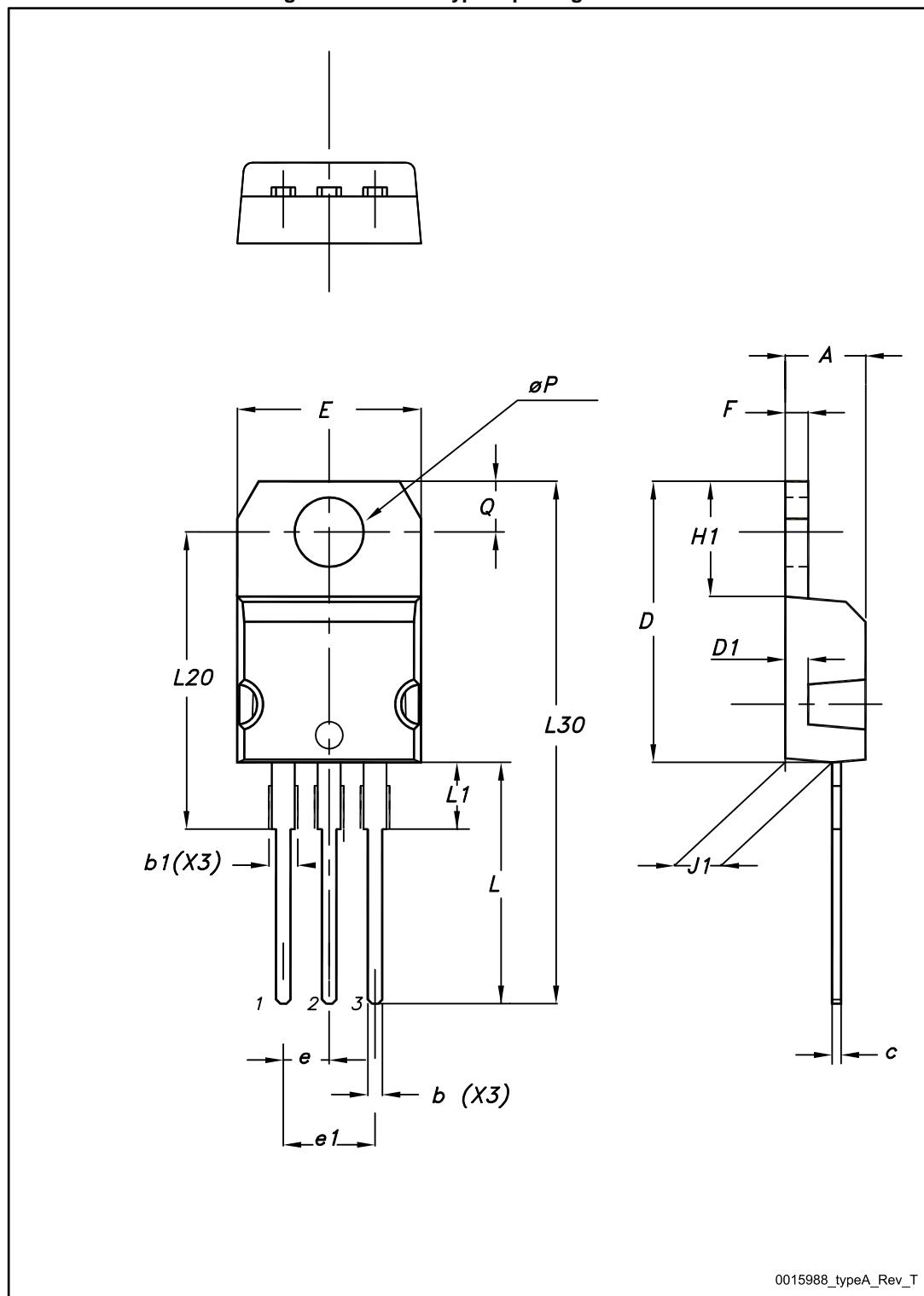


Table 9: TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
01-Apr-2015	1	First release.
21-May-2015	2	Text edits throughout document In Section 2.1 Electrical characteristics (curves): - updated Figure 4: Output characteristics - updated Figure 5: Transfer characteristics

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